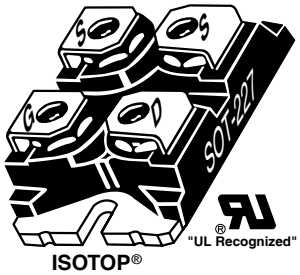
APT40M35JVFR

400V 93A 0.035Ω

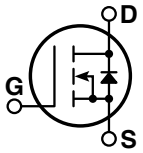
POWER MOS V® FREDFET



ISOTOP®

Power MOS V® is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimizes the JFET effect, increases packing density and reduces the on-resistance. Power MOS V® also achieves faster switching speeds through optimized gate layout.

- **Faster Switching**
- **Lower Leakage**
- **Popular SOT-227 Package**
- **Avalanche Energy Rated**
- **FAST RECOVERY BODY DIODE**



MAXIMUM RATINGS All Ratings: T_C = 25°C unless otherwise specified.

Symbol	Parameter	APT40M35JVFR	UNIT
V_{DSS}	Drain-Source Voltage	400	Volts
I_D	Continuous Drain Current @ T_C = 25°C	93	Amps
I_{DM}	Pulsed Drain Current ①	372	
V_{GS}	Gate-Source Voltage Continuous	±30	Volts
V_{GSM}	Gate-Source Voltage Transient	±40	
P_D	Total Power Dissipation @ T_C = 25°C	700	Watts
	Linear Derating Factor	5.6	W/°C
T_J,T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C
T_L	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I_{AR}	Avalanche Current ① (Repetitive and Non-Repetitive)	93	Amps
E_{AR}	Repetitive Avalanche Energy ①	50	mJ
E_{AS}	Single Pulse Avalanche Energy ④	3600	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage (V_{GS} = 0V, I_D = 250µA)	400			Volts
$I_{D(on)}$	On State Drain Current ② ($V_{DS} > I_{D(on)} \times R_{DS(on)}$ Max, V_{GS} = 10V)	93			Amps
$R_{DS(on)}$	Drain-Source On-State Resistance ② (V_{GS} = 10V, I_D = 46.5A)			0.035	Ohms
I_{DSS}	Zero Gate Voltage Drain Current (V_{DS} = 400V, V_{GS} = 0V)			250	µA
	Zero Gate Voltage Drain Current (V_{DS} = 320V, V_{GS} = 0V, T_C = 125°C)			1000	
I_{GSS}	Gate-Source Leakage Current (V_{GS} = ±30V, V_{DS} = 0V)			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage (V_{DS} = V_{GS}, I_D = 5mA)	2		4	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

DYNAMIC CHARACTERISTICS

APT40M35JVFR

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C_{iss}	Input Capacitance	V_{GS} = 0V		16800	20160	pF
C_{oss}	Output Capacitance	V_{DS} = 25V		2400	3360	
C_{rss}	Reverse Transfer Capacitance	f = 1 MHz		1070	1605	
Q_g	Total Gate Charge ③	V_{GS} = 10V		710	1065	nC
Q_{gs}	Gate-Source Charge	V_{DD} = 200V		80	120	
Q_{gd}	Gate-Drain ("Miller") Charge	I_D = 93A @ 25°C		340	510	
$t_d(on)$	Turn-on Delay Time	V_{GS} = 15V		20	40	ns
t_r	Rise Time	V_{DD} = 200V		30	60	
$t_d(off)$	Turn-off Delay Time	I_D = 93A @ 25°C		75	115	
t_f	Fall Time	R_G = 0.6Ω		14	28	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions		MIN	TYP	MAX	UNIT
I_S	Continuous Source Current (Body Diode)				93	Amps
I_{SM}	Pulsed Source Current ① (Body Diode)				372	
V_{SD}	Diode Forward Voltage ② (V_{GS} = 0V, I_S = - 93A)				1.3	Volts
dv/dt	Peak Diode Recovery dv/dt ⑤				15	V/ns
t_{rr}	Reverse Recovery Time (I_S = -93A, di/dt = 100A/µs)	T_j = 25°C			300	ns
		T_j = 125°C			600	
Q_{rr}	Reverse Recovery Charge (I_S = -93A, di/dt = 100A/µs)	T_j = 25°C		2.2		µC
		T_j = 125°C		9		
I_{RRM}	Peak Recovery Current (I_S = -93A, di/dt = 100A/µs)	T_j = 25°C		16		Amps
		T_j = 125°C		33		

THERMAL/PACKAGE CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.18	°C/W
$R_{\theta JA}$	Junction to Ambient			40	
$V_{Isolation}$	RMS Voltage (50-60 Hz Sinusoidal Waveform From Terminals to Mounting Base for 1 Min.)	2500			Volts
Torque	Maximum Torque for Device Mounting Screws and Electrical Terminations			10	lb•in

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② Pulse Test: Pulse width < 380 µS, Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

④ Starting T_j = +25°C, L = 0.83mH, R_G = 25Ω, Peak I_L = 93A

⑤ $I_S \leq I_D$ = 93A, di/dt = 100A/µs, $T_j \leq 150°C$, R_G = 2.0Ω V_R = 400V.

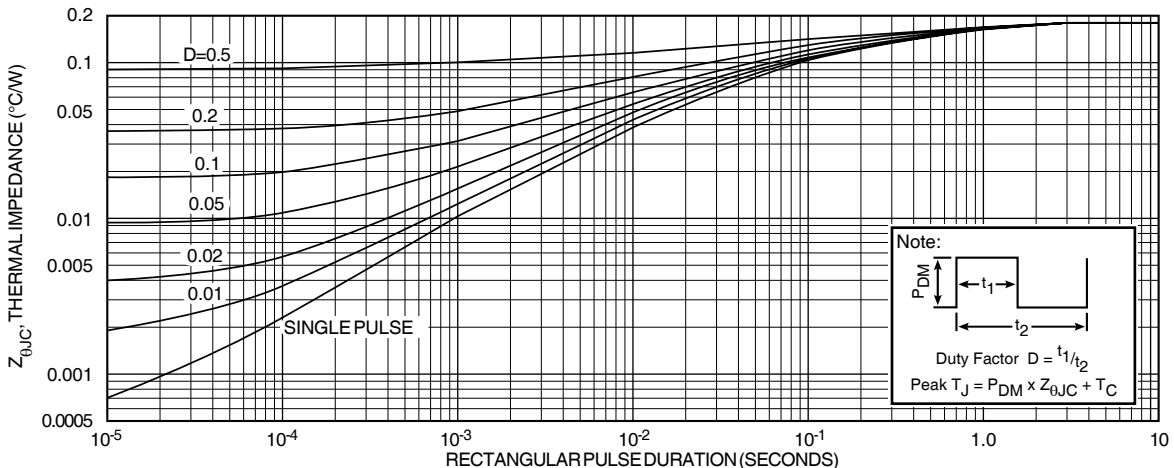


FIGURE 1, MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs PULSE DURATION

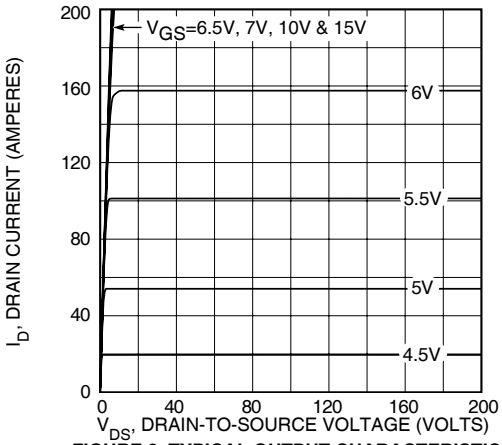


FIGURE 2, TYPICAL OUTPUT CHARACTERISTICS

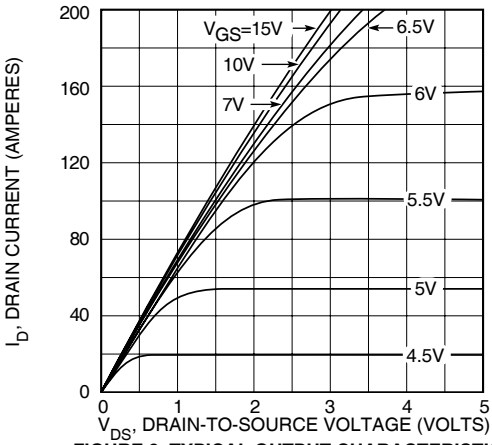


FIGURE 3, TYPICAL OUTPUT CHARACTERISTICS

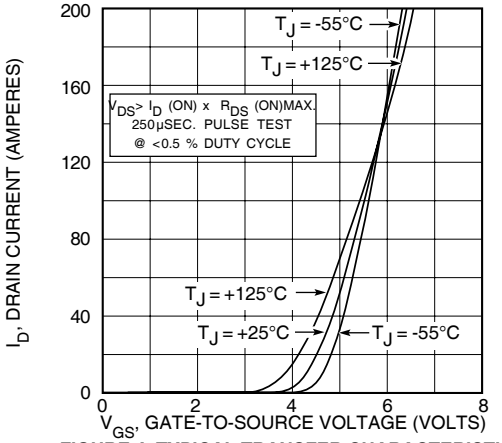


FIGURE 4, TYPICAL TRANSFER CHARACTERISTICS

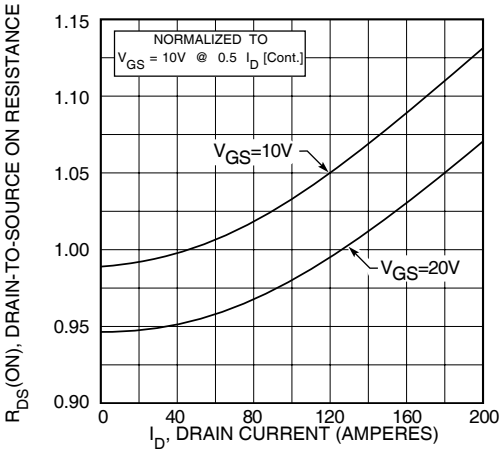


FIGURE 5, R_{DS}(ON) vs DRAIN CURRENT

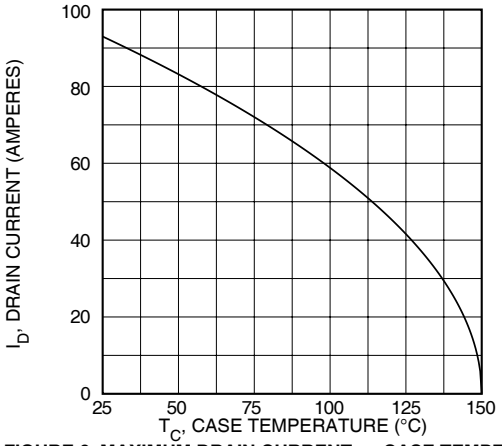


FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE

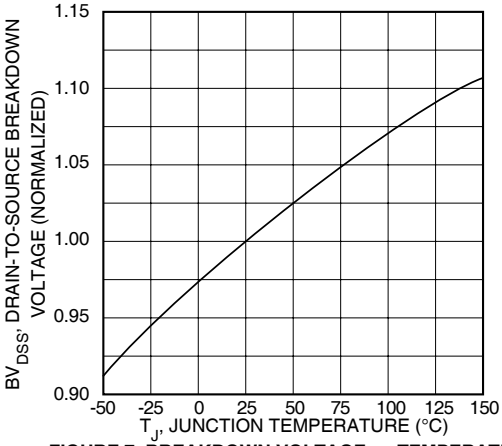


FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE

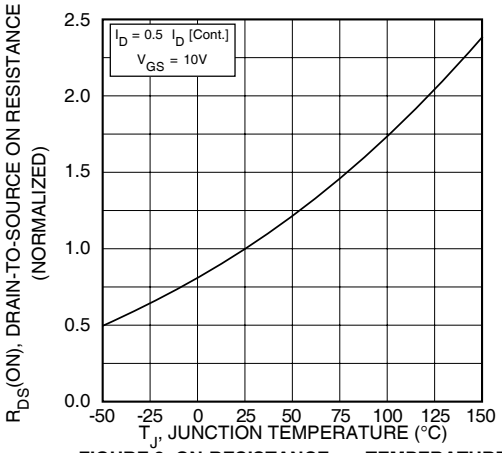


FIGURE 8, ON-RESISTANCE vs. TEMPERATURE

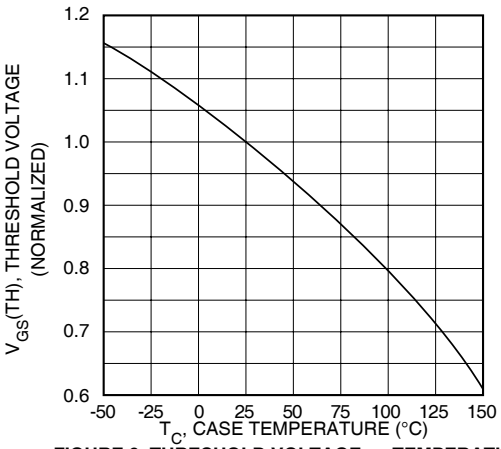


FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE

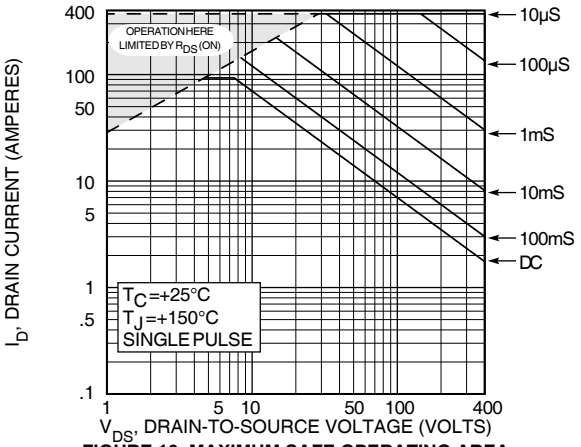


FIGURE 10, MAXIMUM SAFE OPERATING AREA

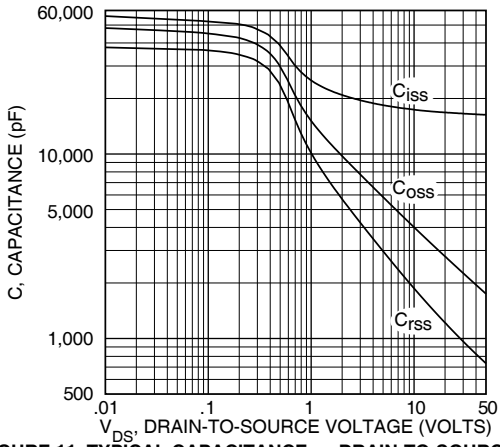


FIGURE 11, TYPICAL CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

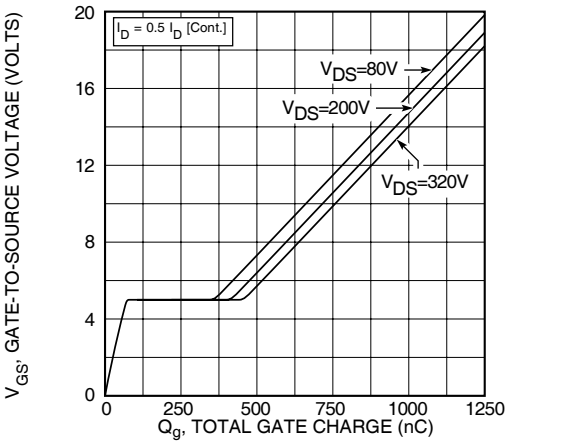


FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE

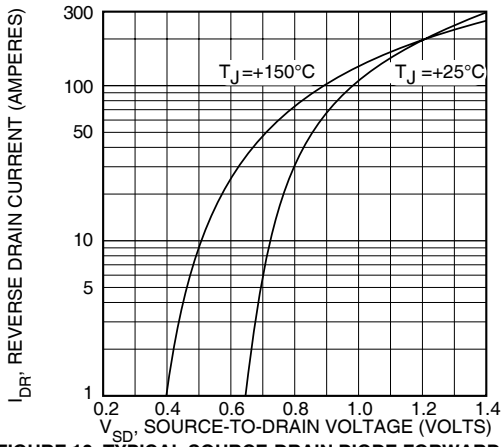
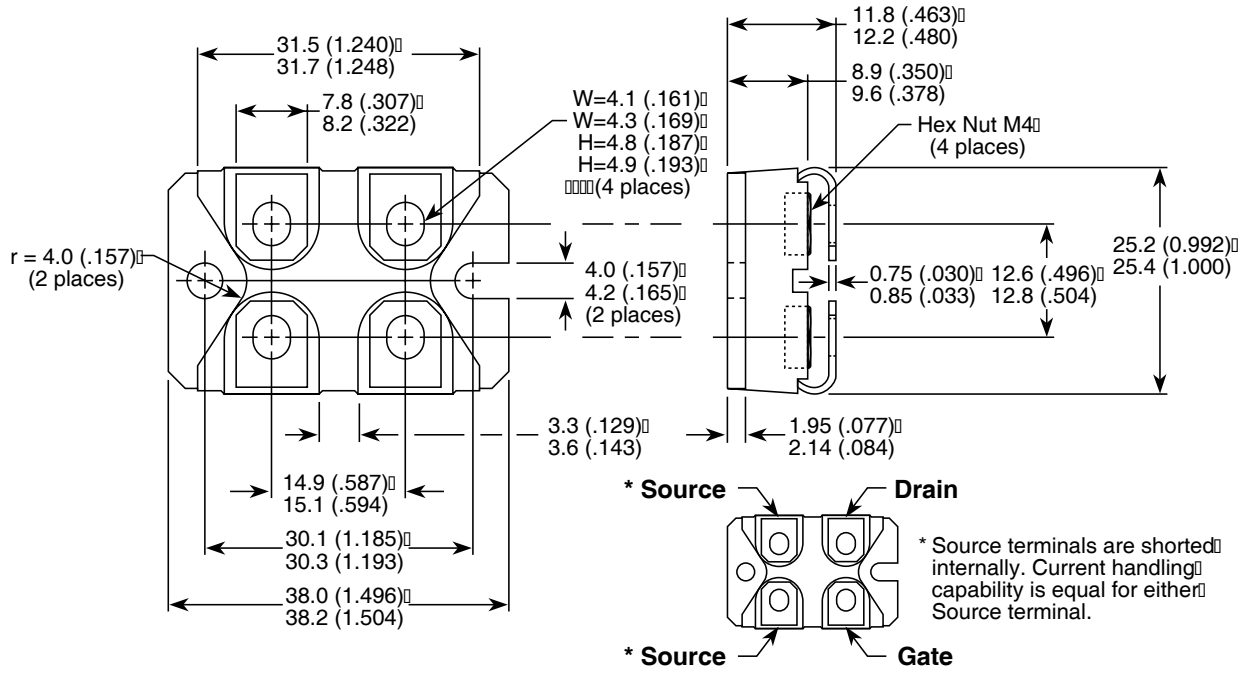


FIGURE 13, TYPICAL SOURCE-DRAIN DIODE FORWARD VOLTAGE

SOT-227 (ISOTOP®) Package Outline



Dimensions in Millimeters and (Inches)

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"UL Recognized" File No. E145592